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Semiconductor devices – Standardization roadmap of fault test method for automotive vehicles

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CONTENTS

FOREWORD 3
1 Scope 5
2 Normative references 5
3 Terms and definitions 5
4 Background 7
4.1 Motivation 7
4.2 Technologies on fault test methods 9
4.2.1 Joint test action group (JTAG) 9
4.2.2 Design for test (DFT) 9
4.2.3 Design for manufacturability (DFM) 10
4.2.4 Scan test 10
5 Standardization roadmap of fault test methods for automotive vehicles 12
Bibliography 14

Figure 1 – Conceptual diagram of environment for semiconductor devices used in automotive vehicles 7
Figure 2 – Regulations on automotive RADAR 8
Figure 3 – Frequency bands for wireless communications 8
Figure 4 – Non-scan and scan cells 11

Table 1 – Standards of frequency band used for V2X 9
Table 2 – Standardization roadmap of fault test methods for semiconductor devices used in automotive vehicles 13

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SEMICONDUCTOR DEVICES – STANDARDIZATION ROADMAP OF FAULT TEST METHOD FOR AUTOMOTIVE VEHICLES

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SEMICONDUCTOR DEVICES – STANDARDIZATION ROADMAP OF FAULT TEST METHOD FOR AUTOMOTIVE VEHICLES

1 Scope

This Technical Report describes standardization roadmap of fault test methods for integrated circuits used in automotive vehicles. Since automotive vehicles are exposed in harsh environment such as very low or high temperature, vibration, high frequency signals, etc. Therefore, they are tested for possible faults which can be caused by harsh environment. There are several fault test methods and related issues to be standardized.

Semiconductor devices used in automotive vehicles are exposed in harsh environment of very high or very low temperature, vibration, high frequency signals, etc. Therefore, they are tested for possible faults which can be caused by harsh environment Evaluation results following this fault test methods will provide robustness of the semiconductor device.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60050-192*, International Electrotechnical Vocabulary (IEV) – Part 192: Dependability*